TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (U-MOSVI-H)

ТРСС8003-Н

High-Efficiency DC-DC Converter Applications Notebook PC Applications Portable Equipment Applications

- Small footprint due to a small and thin package
- High-speed switching
- Small gate charge: Q_{SW} = 4.2 nC (typ.)
- Low drain-source ON-resistance:

 $R_{DS (ON)}$ = 14.3 m Ω (typ.) (V_{GS} = 4.5 V)

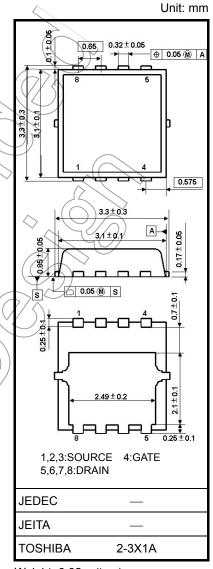
- High forward transfer admittance: $|Y_{fs}| = 33 \text{ S} (typ.)$
- Low leakage current: I_{DSS} = 10 μ A (max) (V_{DS} = 30 V)
- Enhancement mode: V_{th} = 1.3 to 2.3 V (V_{DS} = 10 V, I_D = 0.2 mA)

Absolute Maximum Ratings (Ta = 25°C)

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Characteristic		Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	30	N
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		VDGR	30	<u> </u>
Gate-source voltage		VGSS	±20 V	
Drain current	DC (Note 1)		13	
	Pulsed (Note 1)		39 <	A
Drain power dissipation (Tc = 25°C)		PD	22	- W
Drain power dissipation (t = 10 s) (Note 2a)			1.9	w
Drain power dissipation $(t \neq 10 \text{ s})$ (Note 2b)		→ PD	0.7	w
Single-pulse avalanche energy (Note 3)		EAS	44	mJ
Avalanche current		IAR	13	А
Repetitive avalanche energy (Tc = 25°C) (Note 4)		EAR	1.12	mJ
Channel temperature		Tah	150	°C
Storage temperature range		Tstg	-55 to 150	°C

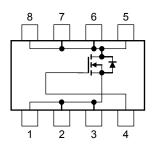
Note: For Notes 1 to 4, refer to the next page.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and



Weight: 0.02 g (typ.)

Circuit Configuration



Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

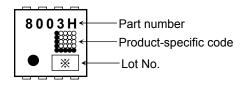
This transistor is an electrostatic-sensitive device. Handle with care.

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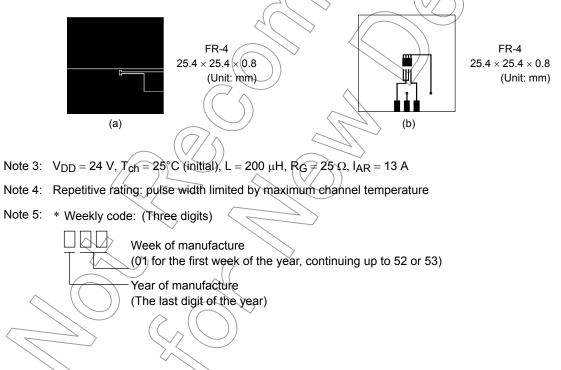
Thermal Characteristics

Characteristic	Symbol	Max	Unit	
Thermal resistance, channel to case (Tc = 25°C)	R _{th (ch-c)}	5.8	°C/W	
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2a)	R _{th (ch-a)}	66	°C/W	
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	180	°C/W	

Marking (Note 5)



- Note 1: Ensure that the channel temperature does not exceed 150°C.
- Note 2: (a) Device mounted on a glass-epoxy board (a)
- (b) Device mounted on a glass-epoxy board (b)



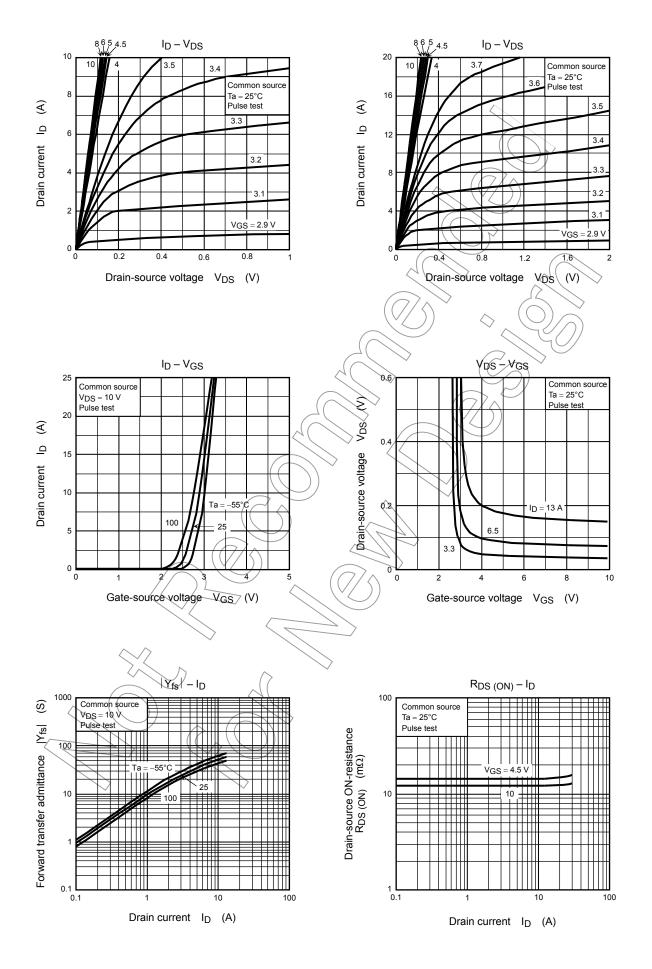
Electrical Characteristics (Ta = 25°C)

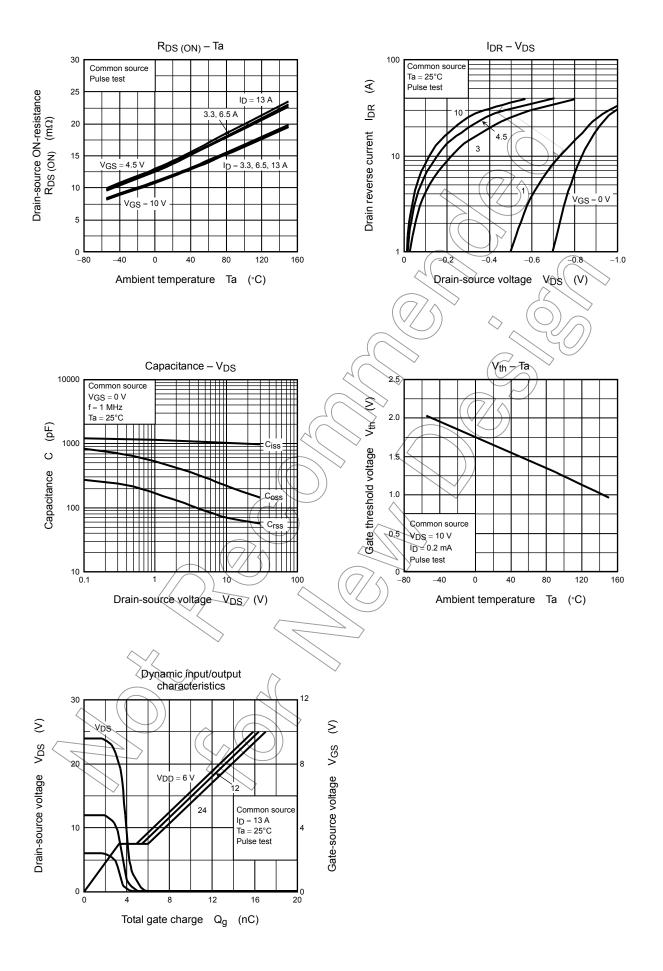
Ch	aracteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS}=\pm 20~V,~V_{DS}=0~V$	_	—	±100	nA
Drain cutoff curre	nt	I _{DSS}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			10	μA
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	30	_	_	V
		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	15		_	v
Gate threshold vo	bltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 0.2 \text{ mA}$	1.3	-7(2.3	V
Drain-source ON-resistance		_	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 6.5 \text{ A}$	77	14.3	19.3	mΩ
		R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 6.5 \text{ A}$	\mathcal{A}	12.2	16.9	
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 6.5 \text{ A}$	17	33		S
Input capacitance		C _{iss}			990	1300	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		63	100	pF
Output capacitance		C _{oss}		_	220	\rightarrow	
Gate resistance		rg	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 5 \text{ MHz}$	-6	0.8	> 1.2	Ω
Switching time	Rise time	tr		K	22) _	
	Turn-on time	t _{on}		$\overline{\langle}$	7.3	_	ns
	Fall time	t _f			2.7	_	
	Turn-off time	toff	Duty \leq 1%, t _w = 10 μ s	_	19	—	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \approx 24 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 13 \text{ A}$		17		
			$V_{DD} \approx 24 \text{ V}, V_{GS} = 5 \text{ V}, I_D \neq 13 \text{ A}$		8.6		
Gate-source char	rge 1	Qgs1		_	3.3		nC
Gate-drain ("Mille	er") charge	Qgd	$V_{DD} \approx 24 V, V_{GS} = 10 V, I_D = 13 A$		2.7		
Gate switch charg	ge (()/	Q _{SW}		_	4.2	_	

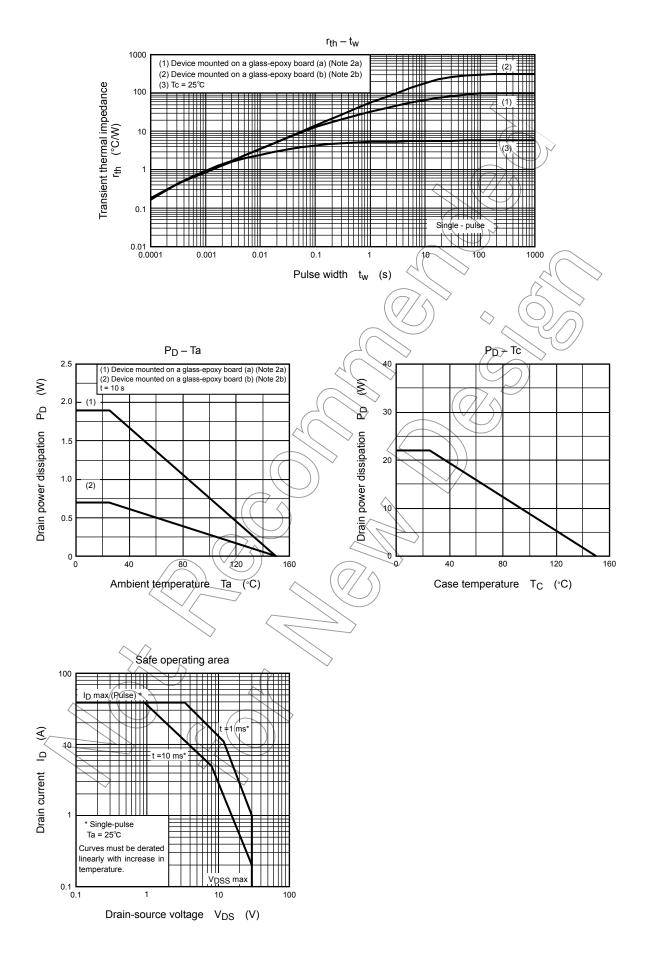
Source-Drain Ratings and Characteristics (Ta = 25° C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current Pulse (Note 1)	I _{DRP}	> -	_	_	39	Α
Forward voltage (diode)	VDSF	I _{DR} = 13 A, V _{GS} = 0 V	_		-1.2	V

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